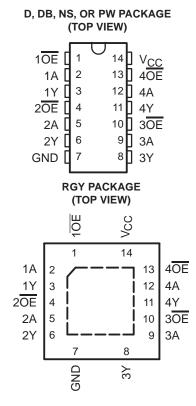
- Operates From 1.65 V to 3.6 V
- Specified From -40°C to 85°C and -40°C to 125°C
- Inputs Accept Voltages to 5.5 V
- Max t<sub>pd</sub> of 4.8 ns at 3.3 V
- Typical V<sub>OLP</sub> (Output Ground Bounce)
  <0.8 V at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C
- Typical V<sub>OHV</sub> (Output V<sub>OH</sub> Undershoot)
  >2 V at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)

### description/ordering information

This quadruple bus buffer gate is designed for 1.65-V to 3.6-V  $V_{CC}$  operation.

The SN74LVC125A features independent line drivers with 3-state outputs. Each output is disabled when the associated output-enable  $(\overline{OE})$  input is high.



To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of this device as a translator in a mixed 3.3-V/5-V system environment.

#### **ORDERING INFORMATION**

TA	PACK	AGE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	QFN – RGY	Reel of 1000	SN74LVC125ARGYR	LC125A
		Tube of 50	SN74LVC125AD	
	SOIC - D	Reel of 2500	SN74LVC125ADR	LVC125A
		Reel of 250	SN74LVC125ADT	
	SOP - NS	Reel of 2000	SN74LVC125ANSR	LVC125A
-40°C to 125°C	SSOP - DB	Reel of 2000	SN74LVC125ADBR	LC125A
		Tube of 90	SN74LVC125APW	
	TSSOP – PW	Reel of 2000	SN74LVC125APWR	LC125A
		Reel of 250	SN74LVC125APWT	

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design quidelines are available at www.ti.com/sc/package.



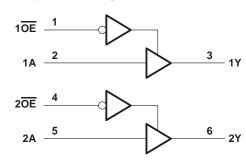
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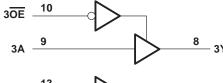


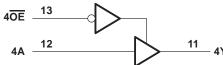
# FUNCTION TABLE (each buffer)

INPU	JTS	OUTPUT
OE	Α	Υ
L	Н	Н
L	L	L
Н	Χ	Z

### logic diagram (positive logic)







# absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	0.5 V to 6.5 V
Input voltage range, V <sub>I</sub> (see Note 1)	0.5 V to 6.5 V
Output voltage range, VO (see Notes 1 and 2)0.	$.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, $I_{ K }(V_1 < 0)$	–50 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)	–50 mA
Continuous output current, IO	±50 mA
Continuous current through V <sub>CC</sub> or GND	
Package thermal impedance, $\theta_{JA}$ (see Note 3): D package	86°C/W
(see Note 3): DB package	96°C/W
(see Note 3): NS package	76°C/W
(see Note 3): PW package	113°C/W
(see Note 4): RGY package	47°C/W
Storage temperature range, T <sub>stq</sub>	
Power dissipation, $P_{tot}$ ( $T_A = -40^{\circ}$ C to 125°C) (see Notes 5 and 6)	

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
  - 2. The value of V<sub>CC</sub> is provided in the recommended operating conditions table.
  - 3. The package thermal impedance is calculated in accordance with JESD 51-7.
  - 4. The package thermal impedance is calculated in accordance with JESD 51-5.
  - 5. For the D package: above 70  $^{\circ}\text{C},$  the value of P  $_{tot}$  derates linearly with 8 mW/K.
  - 6. For the DB, NS, and PW packages: above 60°C, the value of Ptot derates linearly with 5.5 mW/K.



# recommended operating conditions (see Note 7)

			T <sub>A</sub> = 25°C		-40 TO 85°C		-40 TO 125°C		LINUT	
			MIN	MAX	MIN	MAX	MIN	MAX	UNIT	
.,	Owner by conditions	Operating	1.65	3.6	1.65	3.6	1.65	3.6		
VCC	Supply voltage	Data retention only	1.5		1.5		1.5		V	
		V <sub>CC</sub> = 1.65 V to 1.95 V	0.65×V <sub>CC</sub>		0.65×V <sub>CC</sub>		0.65×V <sub>CC</sub>			
٧ıH	High-level input voltage	V <sub>CC</sub> = 2.3 V to 2.7 V	1.7		1.7		1.7		V	
	voltage	V <sub>CC</sub> = 2.7 V to 3.6 V	2		2		2			
		V <sub>CC</sub> = 1.65 V to 1.95 V		0.35×V <sub>CC</sub>		0.35×V <sub>CC</sub>		0.35×V <sub>CC</sub>		
۷ <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 2.3 V to 2.7 V		0.7		0.7		0.7	V	
	voltage	V <sub>CC</sub> = 2.7 V to 3.6 V		0.8		0.8		0.8		
٧ <sub>I</sub>	Input voltage		0	5.5	0	5.5	0	5.5	V	
VO	Output voltage		0	VCC	0	VCC	0	Vcc	V	
		V <sub>CC</sub> = 1.65 V		-4		-4		-4		
	High-level output	V <sub>CC</sub> = 2.3 V		-8		-8		-8	A	
ІОН	current	V <sub>CC</sub> = 2.7 V		-12		-12		-12	mA	
		V <sub>CC</sub> = 3 V		-24		-24		-24		
		V <sub>CC</sub> = 1.65 V		4		4		4		
1	Low-level output	V <sub>CC</sub> = 2.3 V		8		8		8	mA	
lOL	current	V <sub>CC</sub> = 2.7 V		12		12		12	1	
		V <sub>CC</sub> = 3 V		24		24		24	mA	
Δt/Δν	Input transition rise	or fall rate		8		8		8	ns/V	

NOTE 7: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



# SN74LVC125A QUADRUPLE BUS BUFFER GATE WITH 3-STATE OUTPUTS

SCAS290N - JANUARY 1993 - REVISED FEBRUARY 2004

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	TEGT COMPLETIONS	.,	T <sub>A</sub> = 25°C		-40 TO 85°C		-40 TO 125°C				
PARAMETER	TEST CONDITIONS	Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT	
	I <sub>OH</sub> = -100 μA	1.65 V to 3.6 V	V <sub>CC</sub> -0.2			V <sub>CC</sub> -0.2		V <sub>CC</sub> -0.3			
	I <sub>OH</sub> = -4 mA	1.65 V	1.29			1.2		1.05			
.,	I <sub>OH</sub> = -8 mA	2.3 V	1.9			1.7		1.55		.,	
VOH		2.7 V	2.2			2.2		2.05		V	
	I <sub>OH</sub> = -12 mA	3 V	2.4			2.4		2.25			
	I <sub>OH</sub> = -24 mA	3 V	2.3			2.2		2			
	I <sub>OL</sub> = 100 μA	1.65 V to 3.6 V			0.1		0.2		0.3	V	
	I <sub>OL</sub> = 4 mA	1.65 V			0.24		0.45		0.6		
VOL	I <sub>OL</sub> = 8 mA	2.3 V			0.3		0.7		0.75		
	I <sub>OL</sub> = 12 mA	2.7 V			0.4		0.4		0.6		
	I <sub>OL</sub> = 24 mA	3 V			0.55		0.55		8.0		
lį	V <sub>I</sub> = 5.5 V or GND	3.6 V			±1		±5		±20	μΑ	
loz	$V_O = V_{CC}$ or GND	3.6 V			±1		±10		±20	μΑ	
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	3.6 V			1		10		40	μΑ	
ΔlCC	One input at V <sub>CC</sub> – 0.6 V, Other inputs at V <sub>CC</sub> or GND	2.7 V to 3.6 V			500		500		5000	μА	
Ci	V <sub>I</sub> = V <sub>CC</sub> or GND	3.3 V		5						pF	

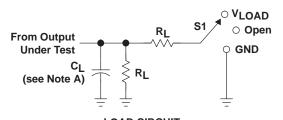
# switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

DADAMETER	FROM	то	.,	T,	4 = 25°C	;	-40 TO	85°C	-40 TO	125°C	
PARAMETER	(INPUT)	(OUTPUT)	v <sub>CC</sub>	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			1.8 V ± 0.15 V	1	4.5	11.8	1	12.3	1	13.8	
		V	2.5 V ± 0.2 V	1	2.7	5.8	1	6.3	1	8.4	
<sup>t</sup> pd	Α	Y	2.7 V	1	3	5.3	1	5.5	1	7	ns
			3.3 V ± 0.3 V	1	2.5	4.6	1	4.8	1	6	
		Y	1.8 V ± 0.15 V	1	4.3	13.8	1	14.3	1	15.8	ns
	ŌĒ		2.5 V ± 0.2 V	1	2.7	6.9	1	7.4	1	9.5	
t <sub>en</sub>			2.7 V	1	3.3	6.4	1	6.6	1	8.5	
			$3.3~\text{V}\pm0.3~\text{V}$	1	2.4	5.2	1	5.4	1	7	
		Y	1.8 V ± 0.15 V	1	4.3	10.6	1	11.1	1	12.6	
			2.5 V ± 0.2 V	1	2.2	5.1	1	5.6	1	7.7	
<sup>t</sup> dis	ŌĒ		2.7 V	1	2.5	4.8	1	5	1	6.5	ns
			$3.3~\text{V}\pm0.3~\text{V}$	1	2.4	4.4	1	4.6	1	6	
t <sub>sk(o)</sub>			3.3 V ± 0.3 V					1		1.5	ns

# operating characteristics, $T_A = 25^{\circ}C$

PARAMETER		TEST CONDITIONS	VCC	TYP	UNIT
			1.8 V	7.4	
C <sub>pd</sub>	Power dissipation capacitance per gate	f = 10 MHz	2.5 V	11.3	pF
			3.3 V	15	

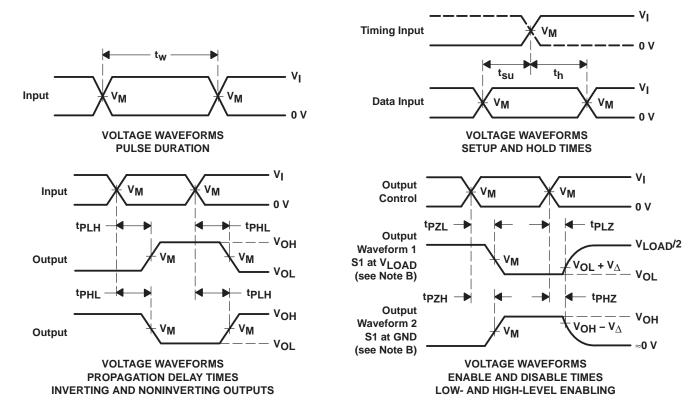
#### PARAMETER MEASUREMENT INFORMATION



TEST	S1
tPLH/tPHL	Open
tPLZ/tPZL	VLOAD
tPHZ/tPZH	GND

LUAD	CIRCUIT

.,	INPUTS		.,	.,	_	В.	V
VCC	٧ <sub>I</sub>	t <sub>r</sub> /t <sub>f</sub>	VM	VLOAD	CL	RL	$v_{\scriptscriptstyle\Delta}$
1.8 V $\pm$ 0.15 V	VCC	≤2 ns	V <sub>CC</sub> /2	2×VCC	30 pF	<b>1 k</b> Ω	0.15 V
2.5 V $\pm$ 0.2 V	VCC	≤ <b>2</b> ns	V <sub>CC</sub> /2	2×VCC	30 pF	<b>500</b> Ω	0.15 V
2.7 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	<b>500</b> Ω	0.3 V
3.3 V $\pm$ 0.3 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	<b>500</b> Ω	0.3 V

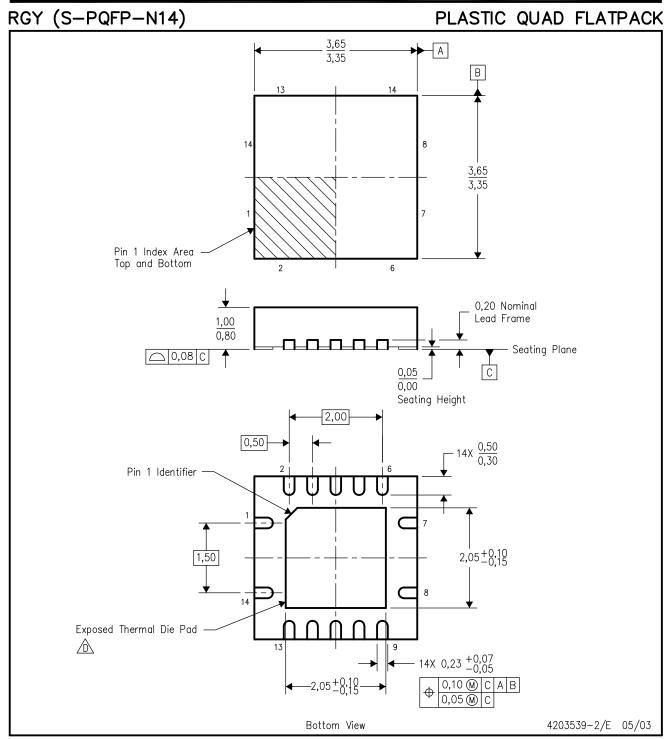


NOTES: A. C<sub>I</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ .
- D. The outputs are measured one at a time, with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzI and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms





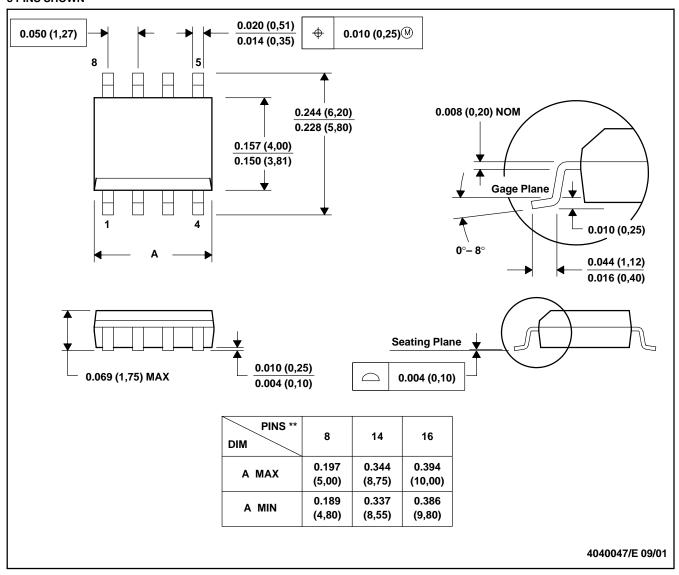
- NOTES: A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. QFN (Quad Flatpack No-Lead) package configuration.
  - The package thermal performance may be enhanced by bonding the thermal die pad to an external thermal plane. This pad is electrically and thermally connected to the backside of the die and possibly selected ground leads.
  - E. Package complies to JEDEC MO-241 variation BA.



#### D (R-PDSO-G\*\*)

#### PLASTIC SMALL-OUTLINE PACKAGE

#### **8 PINS SHOWN**



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-012

# **MECHANICAL DATA**

# NS (R-PDSO-G\*\*)

# 14-PINS SHOWN

#### PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



# DB (R-PDSO-G\*\*)

# PLASTIC SMALL-OUTLINE

#### **28 PINS SHOWN**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

# PW (R-PDSO-G\*\*)

#### 14 PINS SHOWN

# PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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